

2815 TFW



[10191/2251]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s) : SPITZ et al. Confirmation No.: 7205
Serial No. : 10/070,521
Filed : July 8, 2002
For : ARRANGEMENT HAVING P-DOPED AND N-DOPED SEMICONDUCTOR LAYERS, AND METHOD FOR THE MANUFACTURE THEREOF

Examiner : J. Jackson

Art Unit : 2815

Customer No. : 26646

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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on

Date: 11/29/05

Signature: [Signature]

RESPONSE TRANSMITTAL

SIR:

Please find a Response transmitted herewith for filing in the above-identified patent application.

No fee is believed to be required. However, if any fee is required, please use Deposit Account No. 11-0600. A duplicate copy of this transmittal letter is enclosed for that purpose.

Respectfully submitted,

KENYON & KENYON

Dated: 11/29/05

By: [Signature]
B: D2gt (B.N. 41,172)
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Date: 11/29/05
Signature: [Signature]
S. Giustini

RESPONSE

SIR:

In response to the Office Action dated August 29, 2005, reconsideration and allowance of the above-referenced application are requested for the reasons below.

Amendments to the Specification do not appear in this paper.

Amendments to the Claims do not appear in this paper.

Amendments to the Drawings do not appear in this paper.

Remarks begin on page 2 of this paper.